PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

 SUBMISSION TYPE:
 NEW ASSIGNMENT

 NATURE OF CONVEYANCE:
 ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Micron Technology, Inc.	09/26/2008

RECEIVING PARTY DATA

Name:	Aptina Imaging Corporation
Street Address:	c/o Citco Trustees (Cayman) Limited, Regatta Office Park, West Bay Road
City:	Grand Cayman
State/Country:	CAYMAN ISLANDS
Postal Code:	Y1-1205

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	7238977

CORRESPONDENCE DATA

Fax Number: (202)420-2201

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Email: KuoA@dicksteinshapiro.com

Correspondent Name: Dickstein Shapiro LLP
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Address Line 4: Washington, DISTRICT OF COLUMBIA 20006

ATTORNEY DOCKET NUMBER:	M4065.1034/P1034
NAME OF SUBMITTER:	Amy M. Kuo

Total Attachments: 12

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Thomas J. D'Amico - 28,371

Name of Person Signing

DSMDB-2573537v01

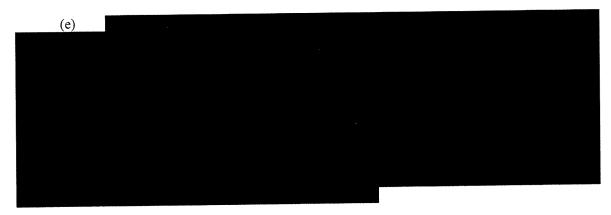
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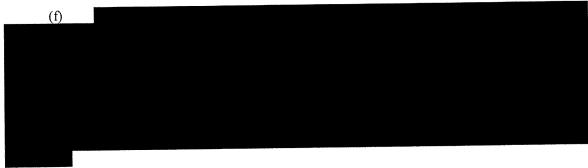
sheet, attachments, and documents:

PATENT ASSIGNMENT AGREEMENT

1. <u>Definitions</u>

- (a) "Agreement" shall mean this Patent Assignment Agreement.
- (b) "Assignee" shall mean **Aptina Imaging Corporation**, a Cayman Islands corporation with offices at c/o Citco Trustees (Cayman) Limited, Regatta Office Park, West Bay Road, Grand Cayman, Y1-1205, Cayman Islands.
- (c) "Assignor" shall mean **Micron Technology, Inc.**, a Delaware corporation with offices at 8000 South Federal Way, Boise, ID 83707.
 - (d) "Effective Date" shall mean October 3, 2008.





- (g) "Imaging Patents" shall mean those patents identified in ATTACHMENT "A" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.
- (h) "Imaging Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "B" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.
- (i) "Semiconductor Patents" shall mean those patents identified in ATTACHMENT "D" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(j) "Semiconductor Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "E" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.

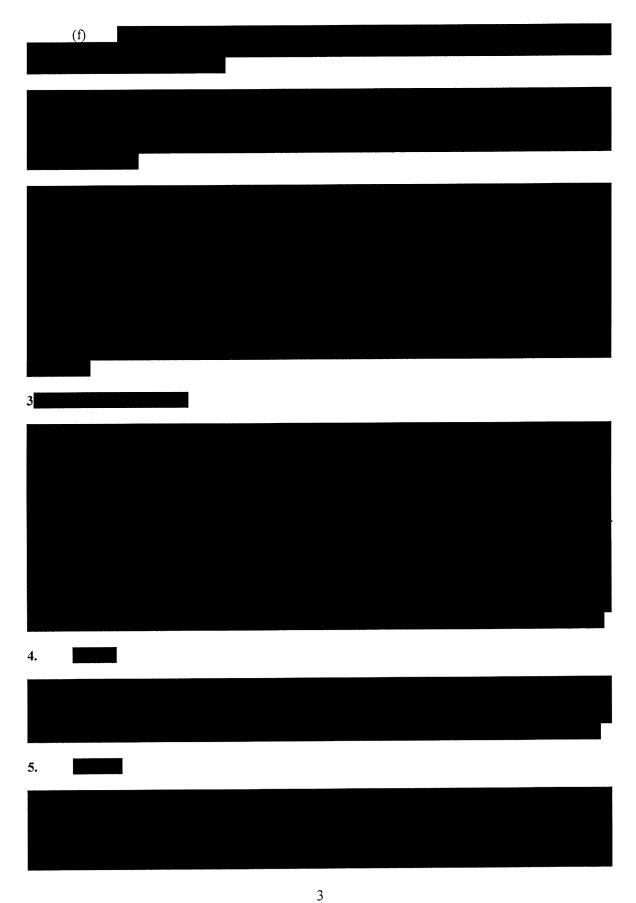


- (a) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Imaging Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Imaging Patents to Assignee.
- (b) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Imaging Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Imaging Patent Applications to Assignee.



- (d) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, and subject further to the restrictions on the Semiconductor Patents set out below, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Semiconductor Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Semiconductor Patents to Assignee.
- (e) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any,

 Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Semiconductor Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Semiconductor Patent Applications to Assignee.





7. General

This Agreement shall be effective as of the Effective Date hereof and shall be binding on the respective heirs, assigns, representatives, and successors of Assignor and of Assignee.

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	Agreed to	by:	•	
	Micron Technology, Inc.			
	Signed:	for Cyles		
	Date:	3/20/08	, 2008	
Notarization State of Idaho County of Ada On 9/26/08, before me, fall (notary name)			•	
who executed this Assignment in my presence and acka authorized capacity for the purposes set forth herein.		ned: fra (
REVIEWED MTI LEGAL	Mý	commission expires: Y	1/12/11	
Notarization State of Idaho	Agreed to Aptina In Signed: Date:	by: naging Corporation Shower I- Ja 9/26/09	wr fr - , 2008	
County of Ada On 7/26/08, before me, Onla R. Chang (notary name) who executed this Assignment in my presence and acknowledges		/ 1		
authorized capacity for the purposes set forth herein. R. Sommand Charles of	Sign My		117/11	

[Signature page to the Patent Assignment Agreement]

ATTACHMENT "A"

IMAGING PATENTS

Aptina Issued

			COUNTRY NAME	LISSUE DATE
PATENT NUMBER	FILE NUMBER			
7217589	2002-0058.01/US	DEEP PHOTODIODE ISOLATION PROCESS	United States of America	May 15, 2007
7217913	AVGO-0009.00/US	METHOD AND SYSTEM FOR WAVELENGTH-DERENDENT IMAGING AND DETECTION USING A HYBRID FILTER	United States of America	- May 15, 2007
7218452	2003-1239.01/US	CONTROLLING LENS SHAPE IN A MICROLENS ARRAY	United States of America	May 15, 2007
7223626	2004-0034.00/U\$	SPACERS FOR PACKAGED MICROELECTRONIC IMAGERS AND METHODS OF MAKING AND USING SPACERS FOR WAFER-LEVEL PACKAGING OF IMAGERS	United States of America	May 29, 2007
7223960	2002-0004.00/US	AN IMAGE SENSOR AN IMAGE SENSOR PIXEL AND METHODS OF FORMING THE SAME	United States of America	May 29, 2007
7230561	2004-0789-00/US	A PROGRAMMABLE INTEGRATING RAMP GENERATOR WITH PEDESTAL	United States of America	Jun 12, 2007
7230645	PBIT-0089.01/US	CMOS APS PIXEL SENSOR DYNAMIC RANGE INCREASE	United States of America	Jun 12, 2007
7233038	2003-0487:01/US	SELF MASKING CONTACT USING AN ANGLED IMPLANT	United States of America	Jun 19, 2007
7233353	PBIT-0132.01/US	IMAGE SENSOR HAVING BOOSTED RESET	United States of America	Jun 19, 2007
7233737	AVGO-0004-00/US	Fixed-focus camera module and associated method of assembly	United States of America	Jun 19; 2007
7238544	2003-0241.01/US	IMAGING WITH GATE CONTROLLED CHARGE STORAGE	United States of America	Jul 3, 2007
.7238977	2003-1330.00/US	WIDE DYNAMIC RANGE SENSOR HAVING A PINNED DIODE WITH MULTIPLE PINNED VOLTAGES	United States of America	Jul 3, 2007
7242332	2005-1148.00/US	COLUMN PARALLEL SIGMA-DELTA ANALOG-TO-DIGITAL CONVERSION WITH GAIN GAIN AND OFFSET CONTROL	United States of America	Jun 20, 2007
7244646	2002-1143.01/US	PIXEL DESIGN TO MAXIMIZE PHOTODIODE CAPACITANCE AND METHOD OF FORMING SAME	United States of America	. jul 17, 2007
7245320	2002-0568.00/US	METHOD AND APPARATUS FOR AUTOMATIC GAIN AND EXPOSURE CONTROL FOR MAINTAINING	United States of America	Jul 17, 2007

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ATTACHMENT "B"

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ATTACHMENT "C"

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ATTACHMENT "D"

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ATTACHMENT "E"

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